

MOS FIELD EFFECT TRANSISTOR 2SK3298

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK3298 is N-channel MOS FET device that features a low gate charge and excellent switching characteristics, designed for high voltage applications such as switching power supply, AC adapter.

ORDERING INFORMATION

PART NUMBER	PACKAGE			
2SK3298	Isolated TO-220			

FEATURES

Low gate charge

QG = 34 nC TYP. (VDD = 450 V, VGS = 10 V, ID = 7.5 A)

- •Gate voltage rating ±30 V
- •Low on-state resistance

RDS(on) = 0.75Ω MAX. (VGS = 10 V, ID = 4.0 A)

- Avalanche capability ratings
- •Isolated TO-220 package

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	600	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±30	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±7.5	Α
Drain Current (Pulse) Note1	D(pulse)	±30	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	2.0	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	40	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	7.5	Α
Single Avalanche Energy Note2	Eas	37.5	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1 %

2. Starting Tch = 25 °C, VDD = 150 V, RG = 25 Ω , VGS = 20 V \rightarrow 0 V

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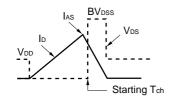
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ELECTRICAL CHARACTERISTICS(TA = 25°C)

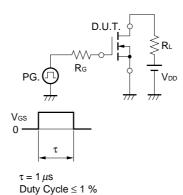
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Leakage Current	IDSS	V _{DS} = 600 V, V _{GS} = 0 V			100	μΑ
Gate Leakage Current	Igss	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	2.5		3.5	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 4.0 A	3.2			S
Drain to Source On-state Resistance	RDS(on)	Vgs = 10 V, ID = 4.0 A		0.67	0.75	Ω
Input Capacitance	Ciss	V _{DS} = 10 V		1580		pF
Output Capacitance	Coss	Vgs = 0 V		280		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		25		pF
Turn-on Delay Time	td(on)	ID = 4.0 A		27		ns
Rise Time	tr	V _{GS(on)} = 10 V		14		ns
Turn-off Delay Time	td(off)	V _{DD} = 150 V		66		ns
Fall Time	tf	$R_G = 10 \Omega$		24		ns
Total Gate Charge	Q _G	ID = 7.5 A		34		nC
Gate to Source Charge	Qgs	V _{DD} = 450 V		8.2		nC
Gate to Drain Charge	Q _{GD}	Vgs = 10 V		12.3		nC
Diode Forward Voltage	V _F (S-D)	IF = 7.5 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 7.5 A, VGS = 0 V		1.6		μs
Reverse Recovery Charge	Qrr	di/dt = 50 A/μs		9.0		μC

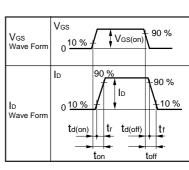
★ TEST CIRCUIT 1 AVALANCHE CAPABILITY

$\begin{array}{c|c} D.U.T. \\ \hline PG. \\ \hline \end{array} \begin{array}{c} S & \Omega \\ \hline \end{array} \begin{array}{c} S & \Omega \\ \hline \end{array} \begin{array}{c} V_{DD} \\ \hline \end{array}$

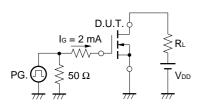


TEST CIRCUIT 2 SWITCHING TIME

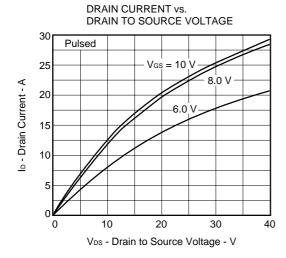


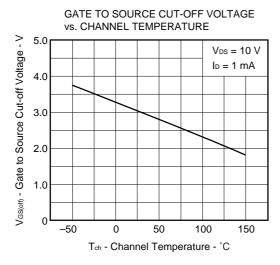


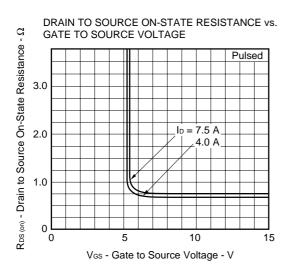
TEST CIRCUIT 3 GATE CHARGE



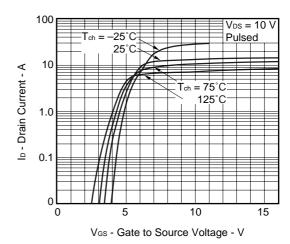
★ TYPICAL CHARACTERISTICS (TA = 25 °C)



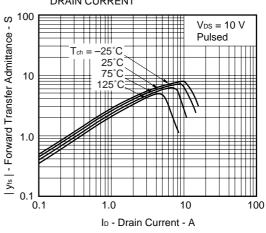


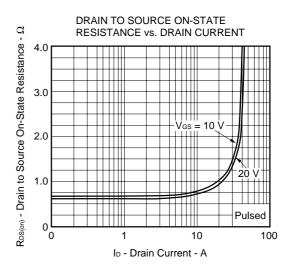


FORWARD TRANSFER CHARACTERISTICS



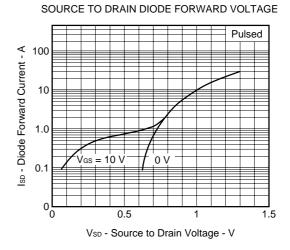
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

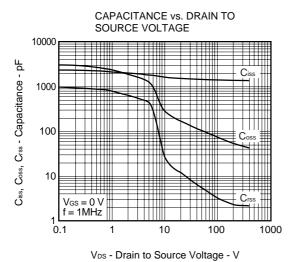


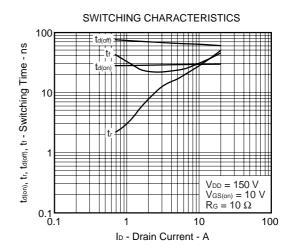


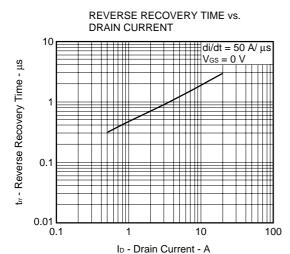
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE G RDS (on) - Drain to Source On-State Resistance -3.0 $I_D = 7.5 A$ 4.0 A 2.0 1.0 $V_{GS} = 10 \text{ V}$ Pulsed 100 0 50 150 -50

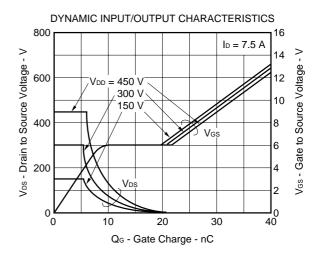
Tch - Channel Temperature - °C

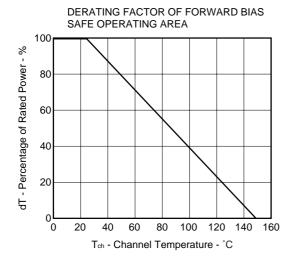


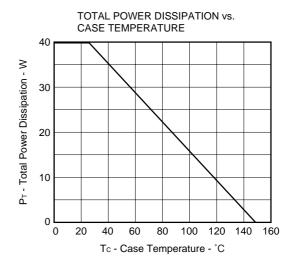


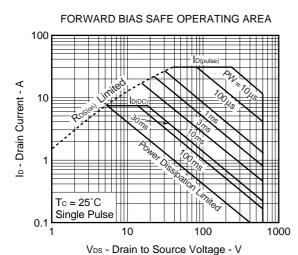


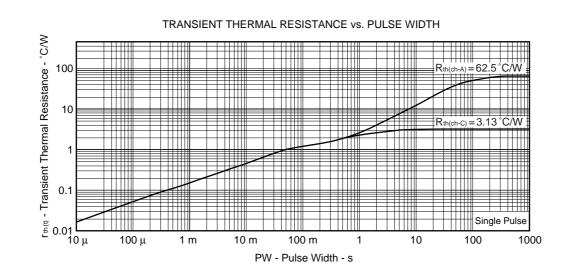


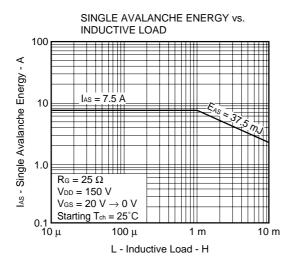


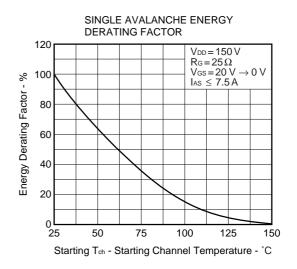






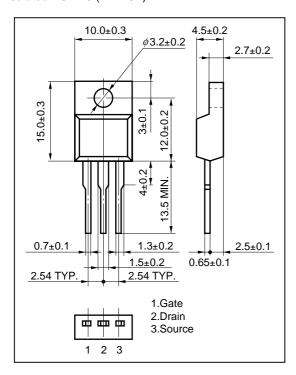




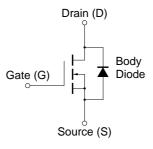


PACKAGE DRAWING (Unit: mm)

Isolated TO-220 (MP-45F)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

[MEMO]

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